



PATENT

2827\$

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/826,512
Filed: April 5, 2001
Title: Wiring Substrate, Method of Manufacturing
Same and Semiconductor Device
Inventors: Michio Horiuchi et al.
Atty. Dkt. No.: 089-01

CERTIFICATE OF MAILING

Date of deposit: September 26, 2002.

I Hereby Certify that this correspondence is
being deposited with the United States Postal
Service in a postage paid envelope addressed to
Commissioner for Patents, Washington, D.C.
20231, with sufficient postage for first class mail
in accordance with 37 C.F.R. § 1.8, on the date
indicated above.

Name of person depositing paper or fee:
Denise Logan

SIGNATURE: Denise Logan

Commissioner For Patents
Washington, D.C. 20231

COVER LETTER WITH CERTIFICATE OF MAIL

Sir:

Enclosed and attached hereto are the following:

- 1) Cover letter with Certificate of Mailing (1 pg.);
- 2) Information Disclosure Statement (2 pgs.);
- 3) Statement under 37 C.F.R. 1.97(e) Accompanying IDS
- 4) PTO-1449 (1 pg.);
- 5) Copies of cited prior art (6 documents);
- 6) Check in the amount of \$180.00 for submission fee; and
- 7) Postcard to be date stamped and returned.

In the event that an additional fee is required with respect to this communication, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Deposit Account No. 16-0750. This cover letter is submitted in triplicate.

Respectfully Submitted,

Ourmazd S. Ojan

Ourmazd S. Ojan
Reg. No. 38,065
Paul & Paul
2900 Two Thousand Market Street
Philadelphia, PA 19103
(215) 568-4900

Date: September 26, 2002

Order No.: 0911

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

at 10
Prior art
FJONES
10-25-02

Serial No.: 09/826,512
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Inventors: Michio Horiuchi et al.
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**INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. 1.97(e)**

Sir/Madam:

Pursuant to the provisions of 37 C.F.R. §§1.56, 1.97 and 1.98, applicant calls the attention of the Examiner to the publications listed on the enclosed sheet of Form PTO-1449. Copies of each publication are submitted herewith. The filing of this Information Disclosure Statement shall not be construed to be an admission that the information cited in the statement is, or is considered to be, material to patentability as described in § 1.56 (b).

It is respectfully requested that the Examiner initial each Form PTO-1449 and return a copy of same upon consideration of these publications.

Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

10/02/2002 HVUONG1 00000014 09826512

01 FC:126

180.00 DP

PATENT



Docket No. 089-01

U.S. PATENTS

<u>Patent No.</u>	<u>Date</u>	<u>Name</u>
5,943,212	Aug 1999	Horiuchi et al.
5,872,393	Feb 1999	Sakai et al.

FOREIGN PATENTS

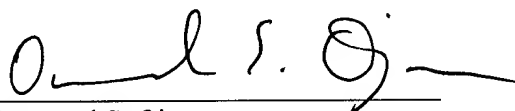
<u>Patent No.</u>	<u>Date</u>	<u>Country</u>
EP 1,030,357 A	Aug 2000	European
WO99/23696 A	May 1999	International
JP 05047842 A	Feb 1993	Japan

OTHER DOCUMENTS

Patent Abstracts of Japan, Vol. 017, No. 344 (E-1390), June 29, 1993 (1993-06-29).

Respectfully submitted,

Date: September 26, 2002


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**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**

Docket No.
089-01

In Re Application Of: **Michio Horiechi and Takashi Kurihara**

Serial No.
09/826,512

Filing Date
April 5, 2001

Examiner

Group Art Unit

Invention: **Wiring Substrate, Method of Manufacturing Same and Semiconductor Device**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

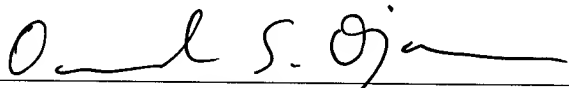
Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- ☒ Each item of information contained in the accompanying information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

Statement Under 37 CFR 1.97(e)(2)

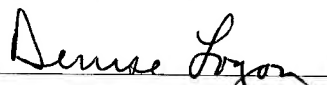
- ☐ No item of information contained in the accompanying information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.


Signature

Dated: September 26, 2002

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I certify that this document is being deposited on
September 26, 2002 with the U.S. Postal Service as first
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Signature of Person Mailing Correspondence

Denise Logan

Typed or Printed Name of Person Mailing Correspondence

CC: